



# STPS10150CT/CG

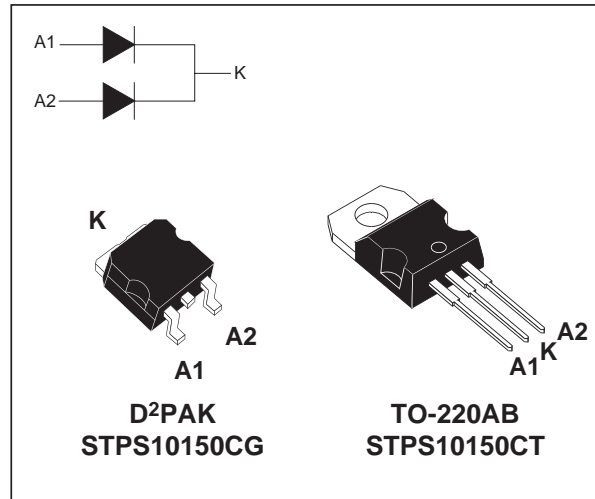
## HIGH VOLTAGE POWER SCHOTTKY RECTIFIER

### MAIN PRODUCT CHARACTERISTICS

$I_{F(AV)}$	2 x 5 A
$V_{RRM}$	150 V
$T_j$	175°C
$V_F(max)$	0.75 V

### FEATURES AND BENEFITS

- HIGH JUNCTION TEMPERATURE CAPABILITY
- GOOD TRADE OFF BETWEEN LEAKAGE CURRENT AND FORWARD VOLTAGE DROP
- LOW LEAKAGE CURRENT
- AVALANCHE CAPABILITY SPECIFIED



### DESCRIPTION

Dual center tap schottky rectifier designed for high frequency Switched Mode Power Supplies.

### ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter			Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage			150	V
$I_{F(RMS)}$	RMS forward current			10	A
$I_{F(AV)}$	Average forward current $\delta = 0.5$	TO-220AB D <sup>2</sup> PAK	$T_c = 155^\circ\text{C}$ per diode per device	5 10	A
$I_{FSM}$	Surge non repetitive forward current		$t_p = 10\text{ ms}$ sinusoidal	120	A
$P_{ARM}$	Repetitive peak avalanche power		$t_p = 1\mu\text{s}$ $T_j = 25^\circ\text{C}$	3100	W
$T_{stg}$	Storage temperature range			- 65 to + 175	°C
$T_j$	Maximum operating junction temperature			175	°C
dV/dt	Critical rate of rise of reverse voltage			10000	V/ $\mu\text{s}$

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## THERMAL RESISTANCES

Symbol	Parameter			Value	Unit
R <sub>th(j-c)</sub>	Junction to case	TO-220AB / D <sup>2</sup> PAK	Per diode	4	°C/W
		TO-220AB / D <sup>2</sup> PAK	Total	2.4	
R <sub>th(c)</sub>		TO-220AB / D <sup>2</sup> PAK	Coupling	0.7	

When the diodes 1 and 2 are used simultaneously :  
 $\Delta T_{j(\text{diode } 1)} = P(\text{diode } 1) \times R_{th(j-c)}(\text{Per diode}) + P(\text{diode } 2) \times R_{th(c)}$

## STATIC ELECTRICAL CHARACTERISTICS (per diode)

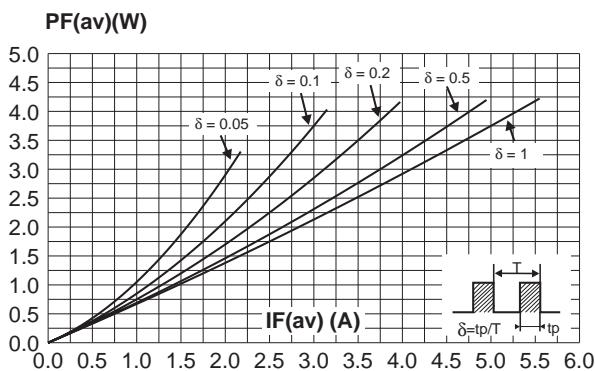
Symbol	Parameter	Tests conditions		Min.	Typ.	Max.	Unit
I <sub>R</sub> *	Reverse leakage current	T <sub>j</sub> = 25°C	V <sub>R</sub> = V <sub>RRM</sub>			2.0	μA
		T <sub>j</sub> = 125°C			0.40	2.0	mA
V <sub>F</sub> **	Forward voltage drop	T <sub>j</sub> = 25°C	I <sub>F</sub> = 5 A			0.92	V
		T <sub>j</sub> = 125°C	I <sub>F</sub> = 5 A		0.69	0.75	
		T <sub>j</sub> = 25°C	I <sub>F</sub> = 10 A			1	
		T <sub>j</sub> = 125°C	I <sub>F</sub> = 10 A		0.79	0.85	

Pulse test : \* tp = 5 ms, δ < 2%  
 \*\* tp = 380 μs, δ < 2%

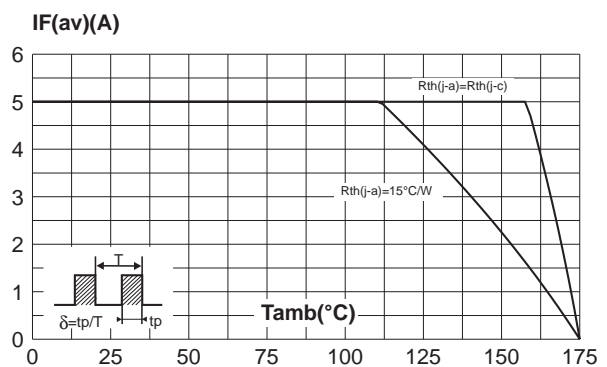
To evaluate the conduction losses use the following equation:

$$P = 0.65 I_{F(AV)} + 0.02 I_{F(RMS)}^2$$

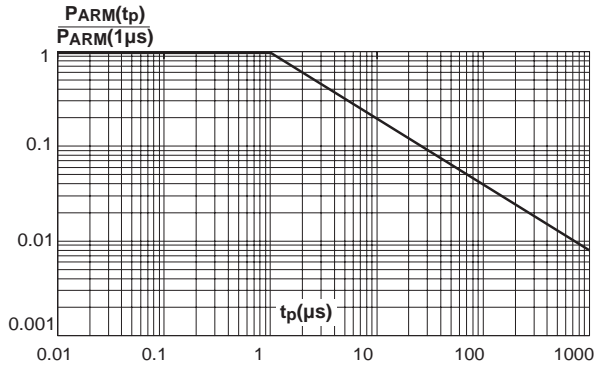
**Fig. 1:** Average forward power dissipation versus average forward current (per diode).



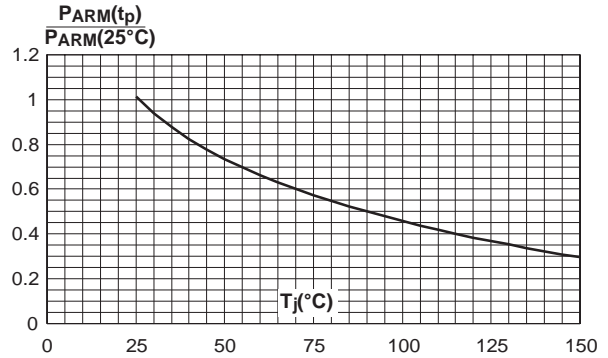
**Fig. 2:** Average forward current versus ambient temperature (δ = 0.5, per diode).



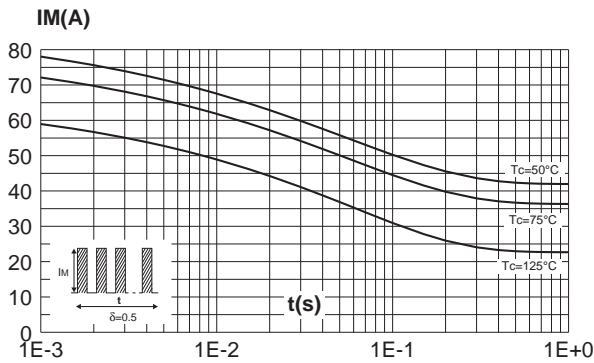
**Fig. 3:** Normalized avalanche power derating versus pulse duration.



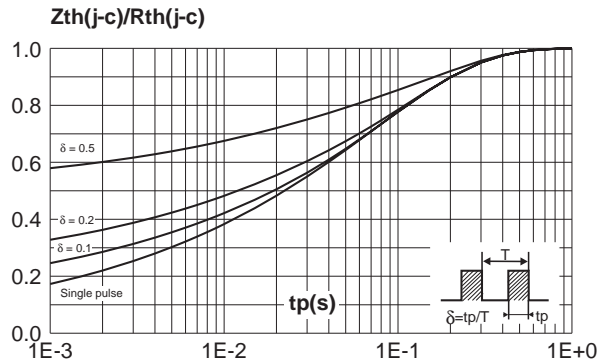
**Fig. 4:** Normalized avalanche power derating versus junction temperature.



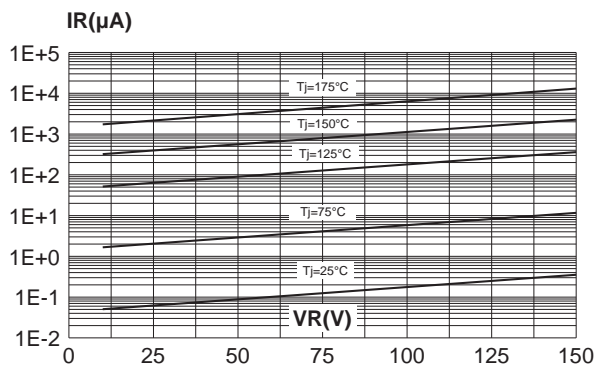
**Fig. 5:** Non repetitive surge peak forward current versus overload duration (maximum values, per diode).



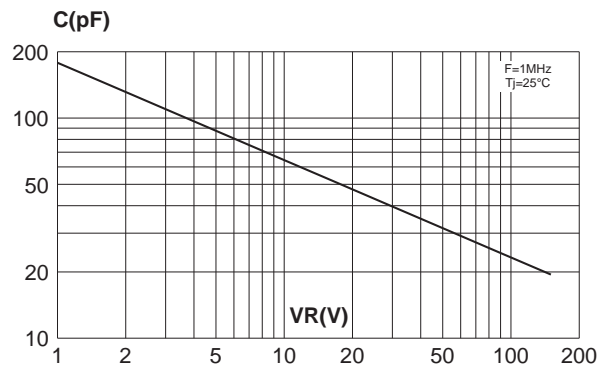
**Fig. 6:** Relative variation of thermal impedance junction to case versus pulse duration (per diode).



**Fig. 7:** Reverse leakage current versus reverse voltage applied (typical values, per diode)

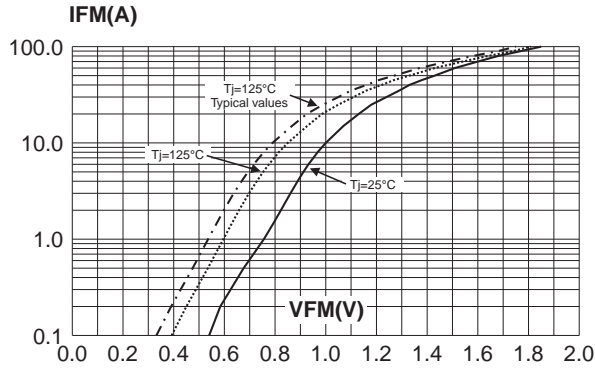


**Fig. 8:** Junction capacitance versus reverse voltage applied (typical values, per diode).

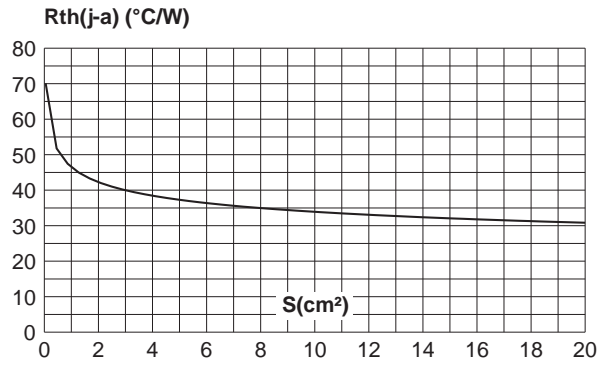


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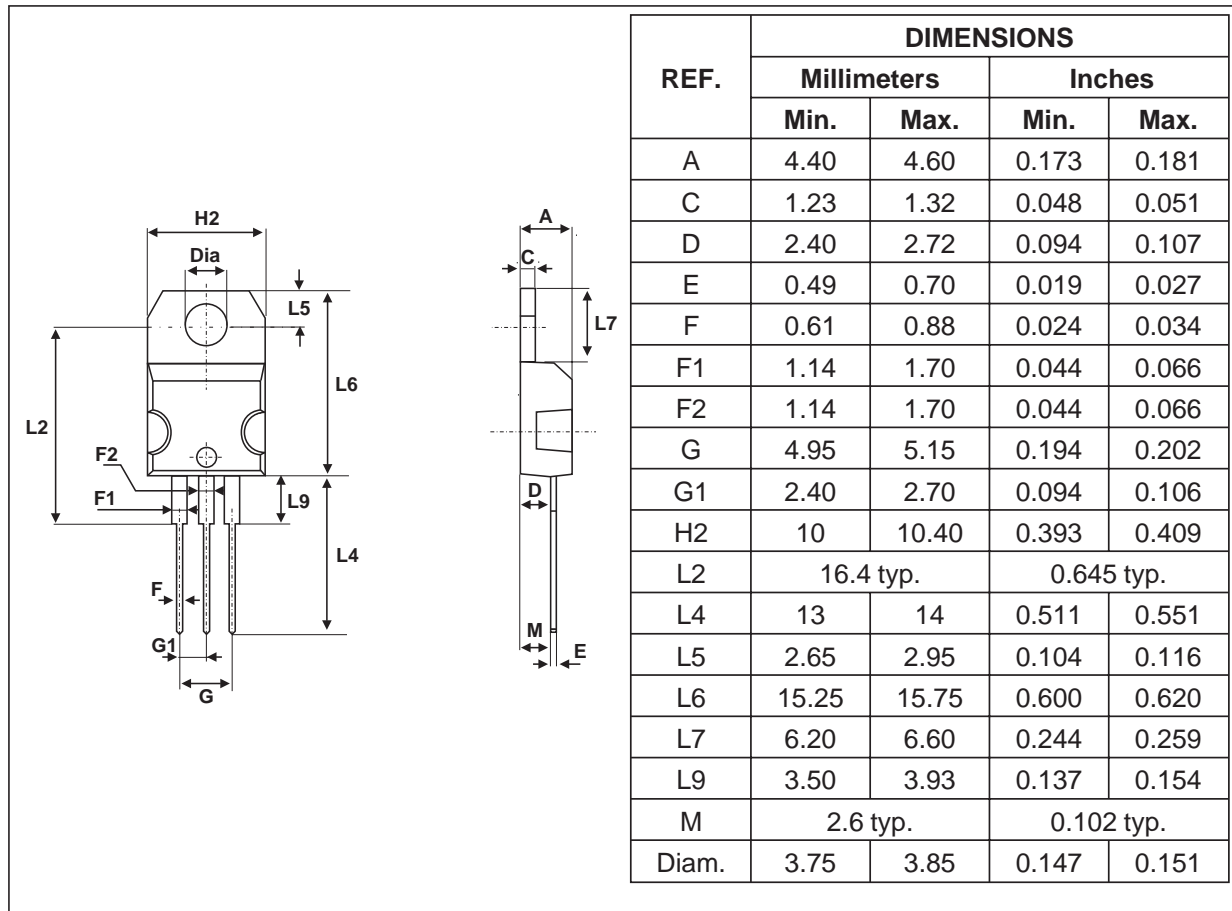
**Fig. 9:** Forward voltage drop versus forward current (maximum values, per diode).



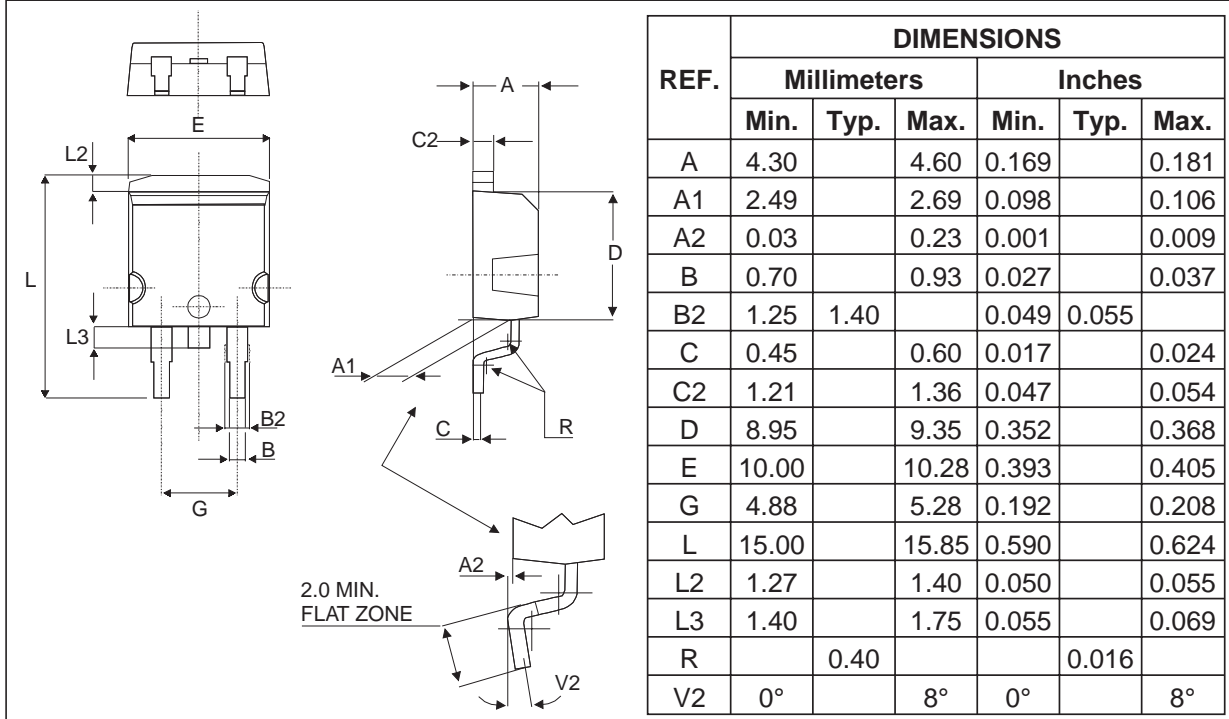
**Fig. 10:** Thermal resistance junction to ambient versus copper surface under tab (Epoxy printed circuit board, copper thickness: 35µm) (STPS10150CG only).



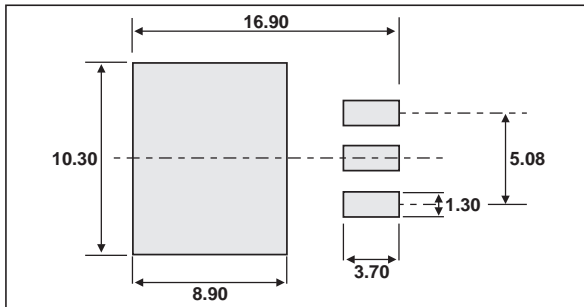
## PACKAGE MECHANICAL DATA TO-220AB



**PACKAGE MECHANICAL DATA**  
D<sup>2</sup>PAK



**FOOT PRINT DIMENSIONS (in millimeters)**



Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS10150CT	STPS10150CT	TO-220AB	2.2 g	50	Tube
STPS10150CG	STPS10150CG	D <sup>2</sup> PAK	1.48 g	50	Tube
STPS10150CG-TR	STPS10150CG	D <sup>2</sup> PAK	1.48 g	1000	Tape & reel

■ EPOXY MEETS UL94, V0

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